

2016 22nd International Workshop on Thermal Investigations of ICs and Systems (THERMINIC 2016)

**Budapest, Hungary
21-23 September 2016**



IEEE Catalog Number: CFP16TII-POD
ISBN: 978-1-5090-5452-7

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IEEE Catalog Number:	CFP16TII-POD
ISBN (Print-On-Demand):	978-1-5090-5452-7
ISBN (Online):	978-1-5090-5451-0

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